ABSTRACT

THERMALLY ENHANCED STACKED DIE PACKAGE AND FABRICATION METHOD

A substrate is provided. A first die is attached to the substrate. The first die is electrically connected to the substrate. A heat sink having an undercut around its periphery is attached to the first die. A second die is attached to the heat sink. The second die is electrically connected to the substrate, and the first die, the heat sink, and the second die are encapsulated. (Fig. 4)